



TC-PEN5-20

Shin-Etsu Silicones of America, Inc.
800-544-1745

Product Description

The TC-PEN series is a reduced density material that maintains the same thermal conductivity and handleability as conventional pads. Suitable for cooling of in-vehicle equipment and other parts that require weight reduction.

Product Features

- Asker C hardness 20
- UL V-0 Equivalent rating
- Available in a variety of thicknesses from .5mm to 5.0mm

Typical Applications

- Large area parts such as lithium-ion batteries
- Devices with non-uniform surfaces

Typical Properties

Type	Soft and Ultra Soft Thermal Pads
Color	Blue
Density @ 23C (g/cm ³)	2.90
Dielectric Strength (kV/mm)	16.0
Thermal Conductivity (W/m·K)	5.20
Thickness (mm)	.5 - 5.0
Sheet Size (mm)	300mm x 400mm

Note: Values are not for specification purposes.

Physical properties are typical for the thickness given. Other thicknesses may have slightly varying properties and are available upon request.

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